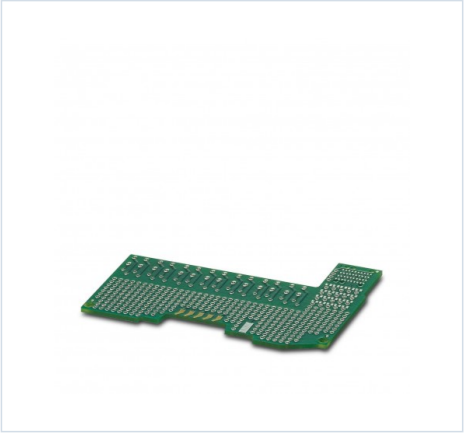
INDUSTRIAL COMPONENT DATA

ME-IO 18,8/28 TBUS DEV-PCB 2202548 PHOENIX CONTACT PCB

Brand: PHOENIX CONTACT | Manufacturer Part Number: ME-IO 18,8/28 TBUS DEV-PCB



Manufacturer	PHOENIX CONTACT
MPN / Reference	ME-IO 18,8/28 TBUS DEV-PCB
Catalog number	2202548
Category	Electronic enclosure
Minimum order	1 Pcs
Document ID	EO-87159513C2
Generated	2026-11-18

Product Overview

PCB
Perforated weft plate for the ME-IO 18.8 DEV-KIT; for HSCH 2.5 base housing; Suitable for manual welding
Perfboard for the ME-IO 18,8 DEV-KIT; for HSCH 2,5 header; ideal for manual soldering

STRUCTURED PRODUCT DATA

Technical Specifications

No structured technical attributes are currently available. Submit an RFQ for technical review.

Classification & Catalog Path

Catalog path	PHOENIX CONTACT > Housing (HS)

Additional Product Information

Technical dataProduct propertiesProduct type PCB
Housing type DIN rail housing
Housing series ME-IO
Product family ME-IO
Max. number of positions 28 (pitch: 5 mm)
DimensionsWidth 1.6 mm
Height 98.2 mm
Depth 66.8 mm
PCB design
PCB thickness 1.4 mm ... 1.8 mm
Material specificationsColor green
Housing material FR 4-21
Environmental and real-life conditionsAmbient conditions

Ambient temperature (operation) 110 °C (depending on power dissipation)
PCB dataThickness of the PCB 1.4 mm ... 1.8 mm

REQUEST PRICE, AVAILABILITY & TECHNICAL REVIEW

Send PHOENIX CONTACT / ME-IO 18,8/28 TBUS DEV-PCB with the required quantity to info@electricaonline.com or use electricaonline.com/request-quote.

GLOBAL OFFICES

Germany: Lise-Meitner-Straße 13, 89081 Ulm | USA: 16225 Park Ten Pl #500, Houston, TX 77084 | UAE: HDS Business Centre Tower, Cluster M, 33rd Floor, JLT, Dubai

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